

ABSTRACT

A method of packaging a multi chip module (MCM) with low cost and high reliability is disclosed. In the MCM process, a plurality of bare chips and CPSs, such as CPU or memory device, are integrated on a substrate to
5 increase the package density. The method discards the high cost KGD process and directly takes the thin and small CSPs passing the tests as KGD and integrates the chips and CSPs into ball grid array package (BGA package) so that the cost is reduced and the yield and quality of the package is improved.